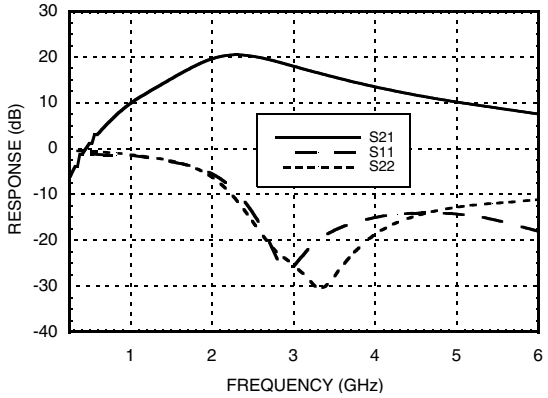
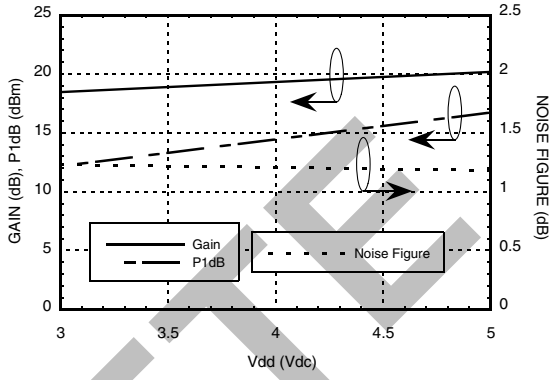
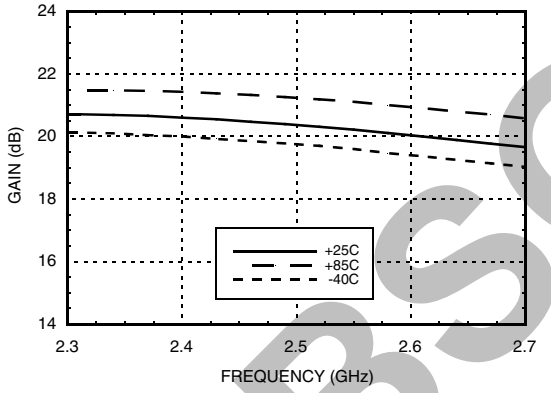
LNA Broadband Gain & Return Loss



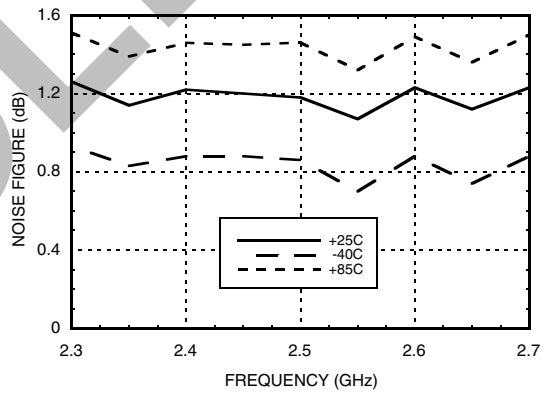
LNA Gain, Noise Figure & Power vs. Supply Voltage @ 2.5 GHz



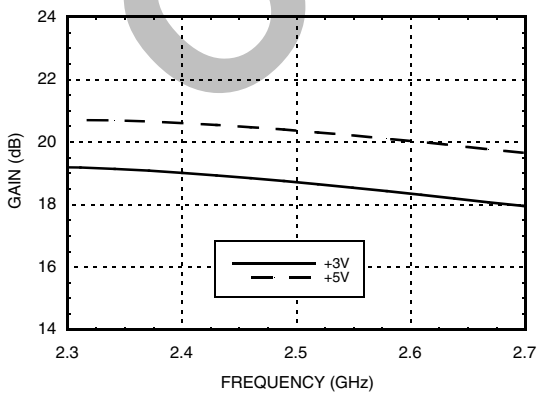
LNA Gain vs. Temperature



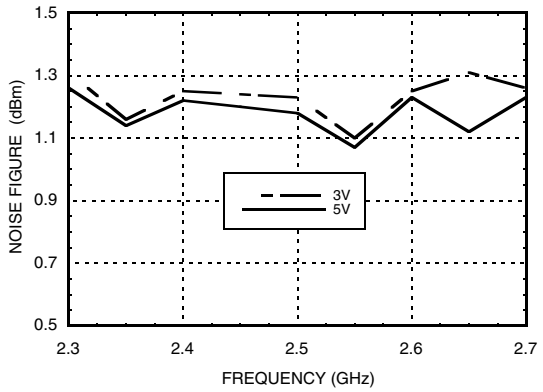
LNA Noise Figure vs. Temperature



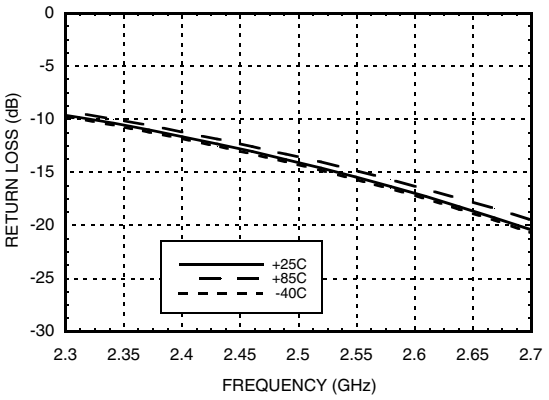
LNA Gain vs. Vdd



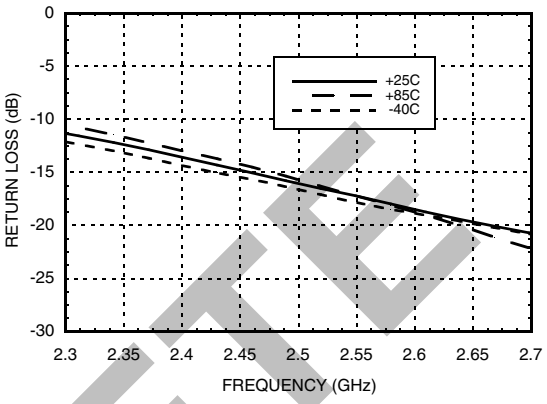
LNA Noise Figure vs. Vdd



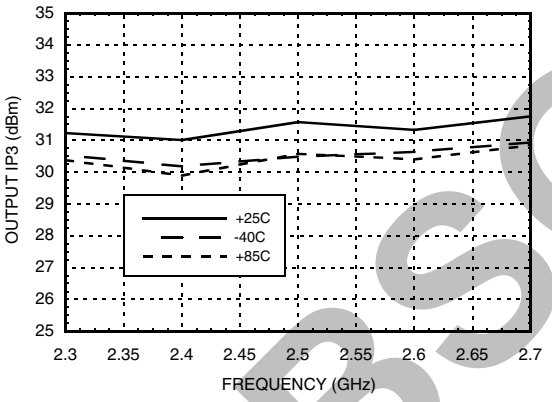
LNA Input Return Loss vs. Temperature



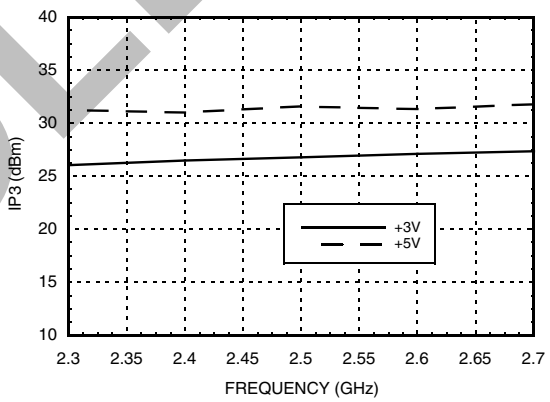
LNA Output Return Loss vs. Temperature



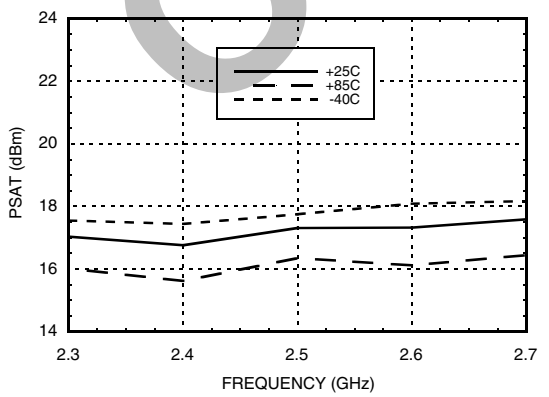
LNA Output IP3 vs. Temperature



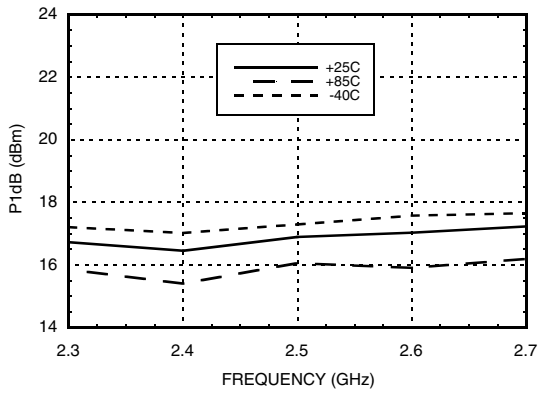
LNA Output IP3 vs. Vdd



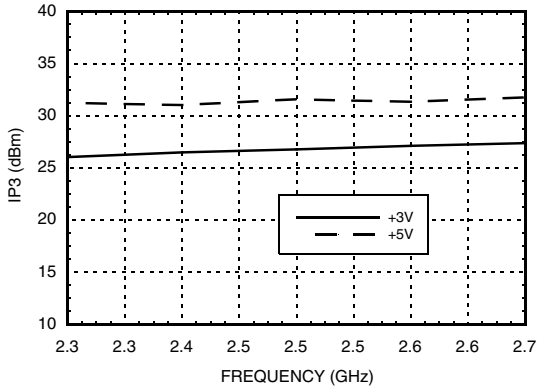
LNA Psat vs. Temperature



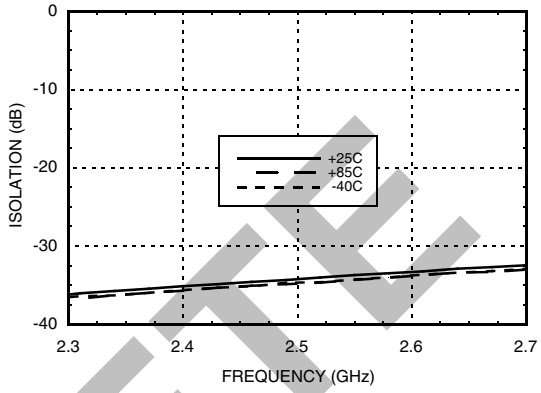
LNA Output P1dB vs. Temperature



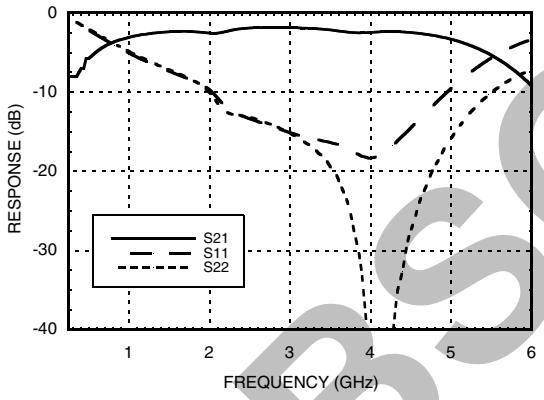
LNA Output P1dB vs. Vdd



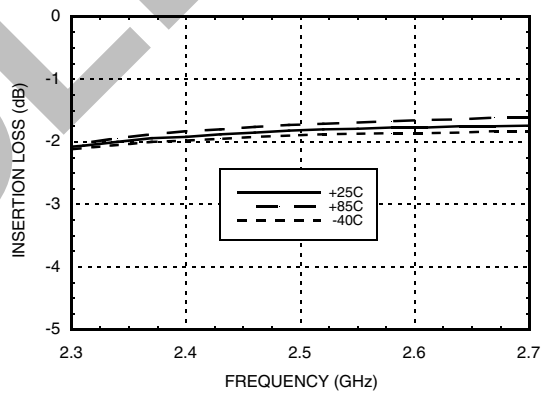
LNA Reverse Isolation vs. Temperature



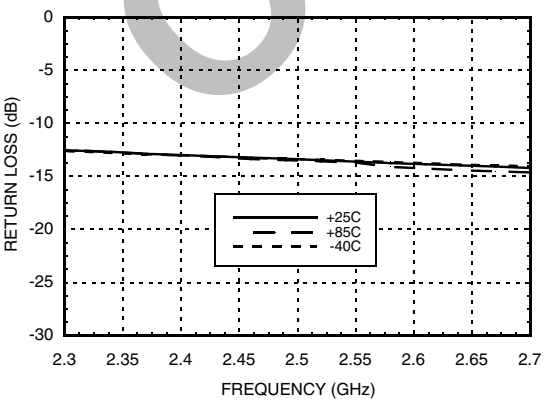
Bypass Mode Broadband Gain & Return Loss



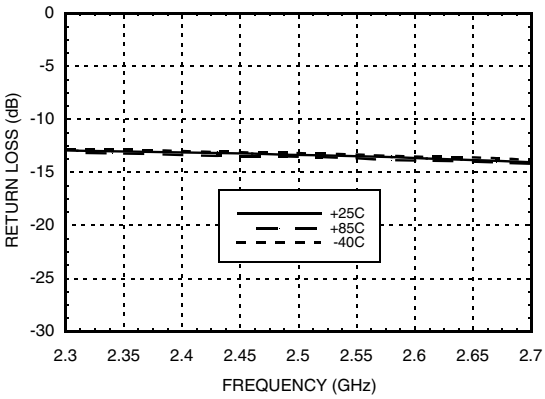
Bypass Mode Insertion Loss vs. Temperature



Bypass Mode Input Return Loss vs. Temperature [1]



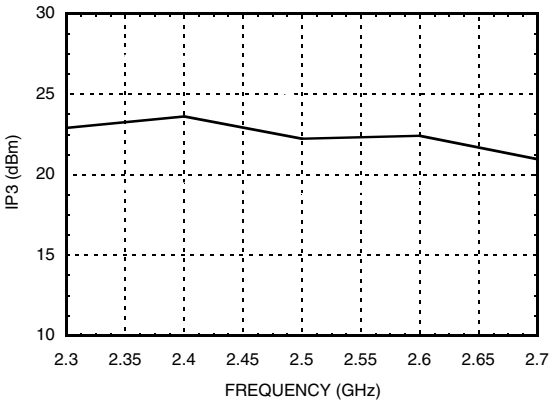
Bypass Mode Output Return Loss vs. Temperature [1]



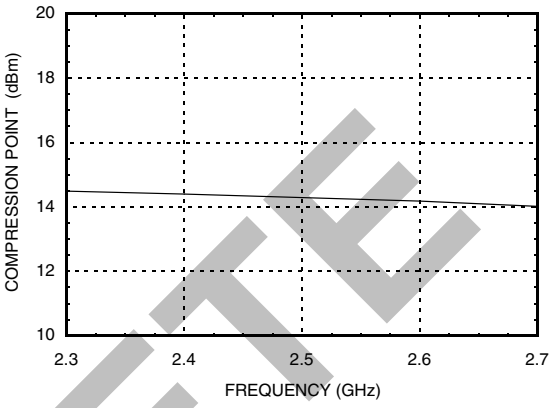
RoHS✓ EARTH FRIENDLY

GAAS PHEMT MMIC LOW NOISE AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz

Bypass Mode Input IP3 vs. Frequency



Bypass Mode Input P1dB vs. Frequency



GAAS PHEMT MMIC LOW NOISE AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz

Absolute Maximum Ratings

Drain Bias Voltage (Vdd)		+8 Vdc
RF Input Power (RFIN) (Vdd = +5.0 Vdc)	LNA Mode Bypass Mode	+22 dBm +30 dBm
Channel Temperature		150 °C
Continuous Pdiss (T = 85 °C) (derate 15.85 mW/°C above 85 °C)		1.03 mW
Thermal Resistance (channel to ground paddle)		63.08 °C/W
Storage Temperature		-65 to +150° C
Operating Temperature		-40 to +100° C

Typical Supply Current vs. Vdd

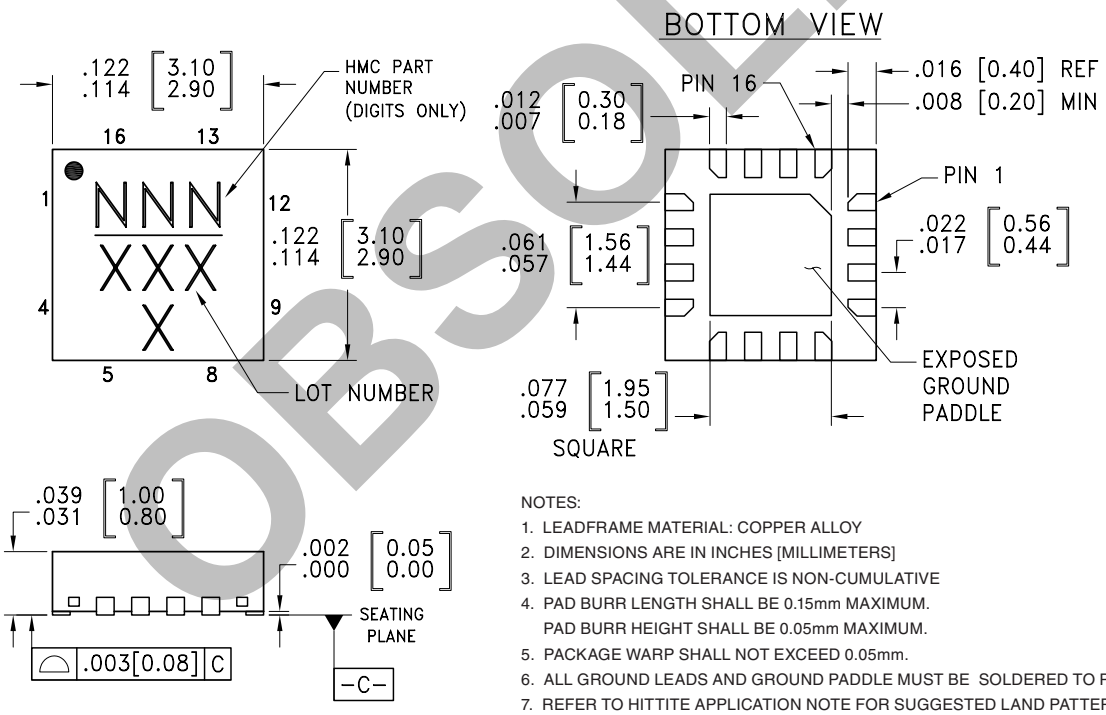
Vdd (Vdc)	Idd (mA)
+3.0	28
+5.0	74

Truth Table

LNA Mode	Vctl= Vdd ± 0.3V
Bypass Mode	Vctl= 0 ± 0.3V

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing



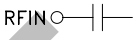
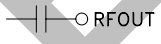
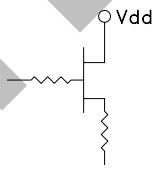
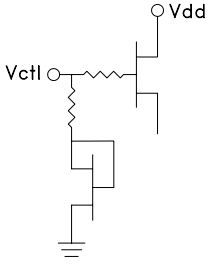
NOTES:
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC605LP3	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	605 XXXX
HMC605LP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	605 XXXX

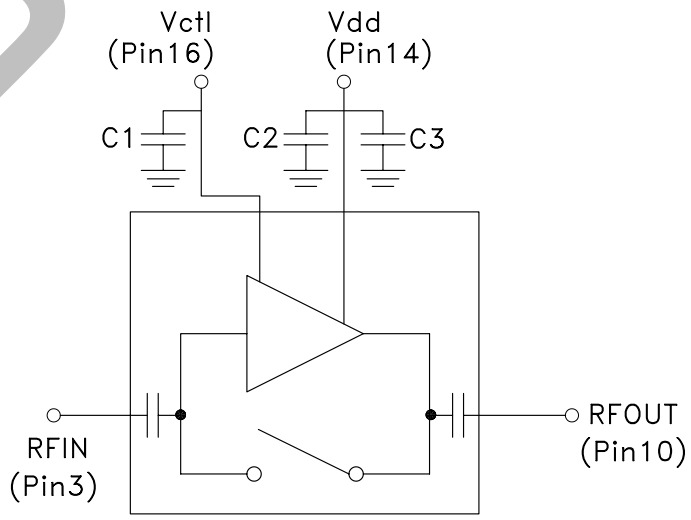
[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX

Pin Descriptions

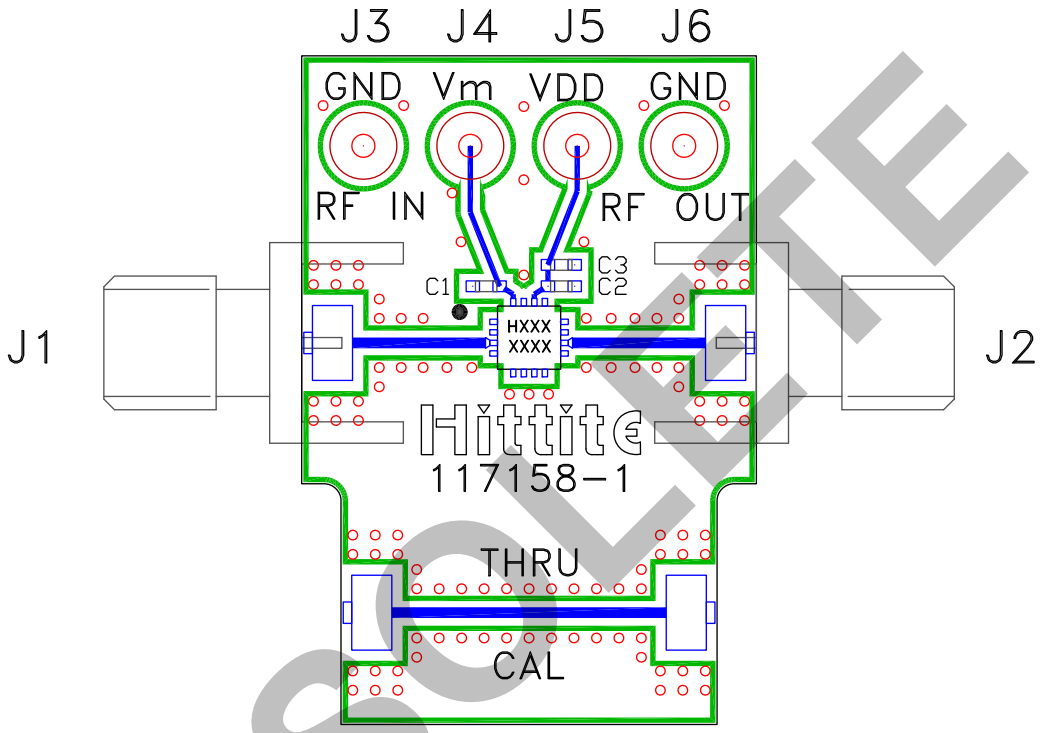
Pin Number	Function	Description	Interface Schematic
1, 2, 5, 6, 8, 12	N/C	No connection necessary. These pins may be connected to RF/DC ground.	
3	RFIN	This pin is AC coupled and matched to 50 Ohms.	
4, 7, 9, 11, 15	GND	These pins must be connected to RF/DC ground.	
10	RFOUT	This pin is AC coupled and matched to 50 Ohms.	
14	Vdd	Power supply voltage. Bypass capacitors are required. See application circuit.	
16	Vctl	LNA/Bypass Mode Control Voltage. See truth table.	

Application Circuit

Components	Value
C1, C2	100pF
C3	10KpF



Evaluation PCB



List of Materials for Evaluation PCB 117160 [1]

Item	Description
J1 - J2	PCB Mount SMA RF Connector
J3 - J6	DC Pin
C1, C2	100 pF Capacitor, 0402 Pkg.
C3	10 KpF Capacitor, 0402 Pkg.
U1	HMC605LP3 / 605LP3E Amplifier
PCB [2]	117158 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.